

Jeremy Rodgers has worked nearly 18 years in several areas of electronics hardware design; traditional and advanced microelectronics packaging, PCB schematic design and layout, and RF/microwave modeling and simulation along with SI/PI analysis. Mr. Rodgers experience in advanced microelectronics packaging has given him the opportunity to produce package designs in HDI laminate based MCMs, 2.5D Si interposer with TSVs, multi-layer additive electronics / printed hybrid electronics (PHE), and FOWLP. Mr. Rodgers earned his BA degree in Electrical Engineering from UMD College Park in 2004 and his MA degree in Electrical Engineering from Johns Hopkins in 2010, focusing on RF Design. Mr. Rodgers currently serves as a technical director within the Hardware Solutions division at NSA.